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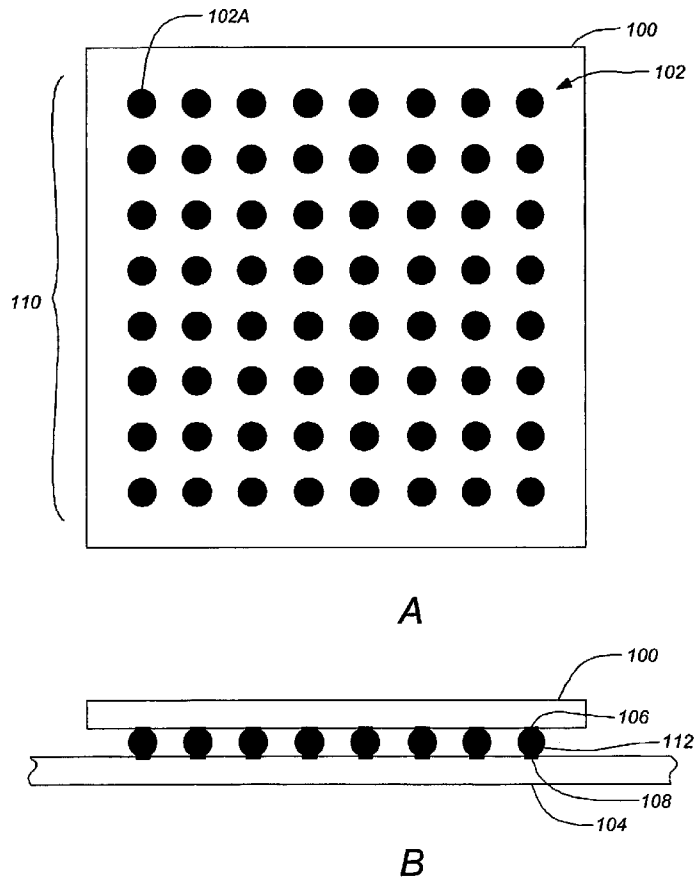
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(54) Title: BALL GRID ARRAY X-RAY ORIENTATION MARK



(57) Abstract: An apparatus and method for inspecting electronic component orientation along with x-ray verification of connection integrity is presented. An exemplary method comprises providing an electronic component 100 for surface mount integration and providing an x-ray visible orientation indicator 300, 402, 500, 600 for the electronic component 100 such that proper orientation of the electronic component 100 is verifiable by x-ray inspection after performing surface mount integration of the electronic component. The x-ray inspection also makes connection integrity of the electronic component 100 verifiable.

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